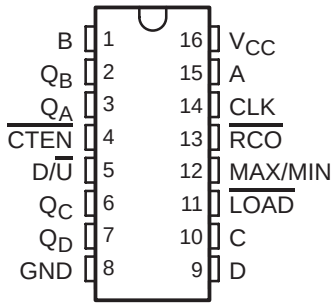
- **2-V to 6-V V_{CC} Operation ('HC190, 191)**
- **4.5-V to 5.5-V V_{CC} Operation ('HCT191)**
- **Wide Operating Temperature Range of −55°C to 125°C**
- **Synchronous Counting and Asynchronous Loading**
- **Two Outputs for n-Bit Cascading**
- **Look-Ahead Carry for High-Speed Counting**
- **Balanced Propagation Delays and Transition Times**
- **Standard Outputs Drive Up To 15 LS-TTL Loads**
- **Significant Power Reduction Compared to LS-TTL Logic ICs**

CD54HC190, 191; CD54HCT191 . . . F PACKAGE
CD74HC190 . . . E, NS, OR PW PACKAGE
CD74HC191, CD74HCT191 . . . E OR M PACKAGE
(TOP VIEW)



description/ordering information

The CD54/74HC190 are asynchronously presettable BCD decade counters, whereas the CD54/74HC191 and CD54/74HCT191 are asynchronously presettable binary counters.

Presetting the counter to the number on preset data inputs (A−D) is accomplished by a low asynchronous parallel load ($\overline{LOAD}$) input. Counting occurs when $\overline{LOAD}$ is high, count enable ($\overline{CTEN}$) is low, and the down/up (D/$\overline{U}$) input is either high for down counting or low for up counting. The counter is decremented or incremented synchronously with the low-to-high transition of the clock.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−55°C to 125°C	PDIP − E	Tube of 25	CD74HC190E	CD74HC190E
			CD74HC191E	CD74HC191E
			CD74HCT191E	CD74HCT191E
	SOIC − M	Tube of 40	CD74HC191M	HC191M
		Reel of 2500	CD74HC191M96	
		Reel of 250	CD74HC191MT	
		Tube of 40	CD74HCT191M	HCT191M
	SOP − NS	Reel of 2000	CD74HC190NSR	HC190M
	TSSOP − PW	Tube of 90	CD74HC190PW	HJ190
		Reel of 2000	CD74HC190PWR	
		Reel of 250	CD74HC190PWT	
	CDIP − F	Tube of 25	CD54HC190F3A	CD54HC190F3A
			CD54HC191F3A	CD54HC191F3A
			CD54HCT191F3A	CD54HCT191F3A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

description/ordering information (continued)

When an overflow or underflow of the counter occurs, the MAX/MIN output, which is low during counting, goes high and remains high for one clock cycle. This output can be used for look-ahead carry in high-speed cascading (see Figure 1). The MAX/MIN output also initiates the ripple clock ($\overline{RCO}$) output, which normally is high, goes low, and remains low for the low-level portion of the clock pulse. These counters can be cascaded using $\overline{RCO}$ (see Figure 2).

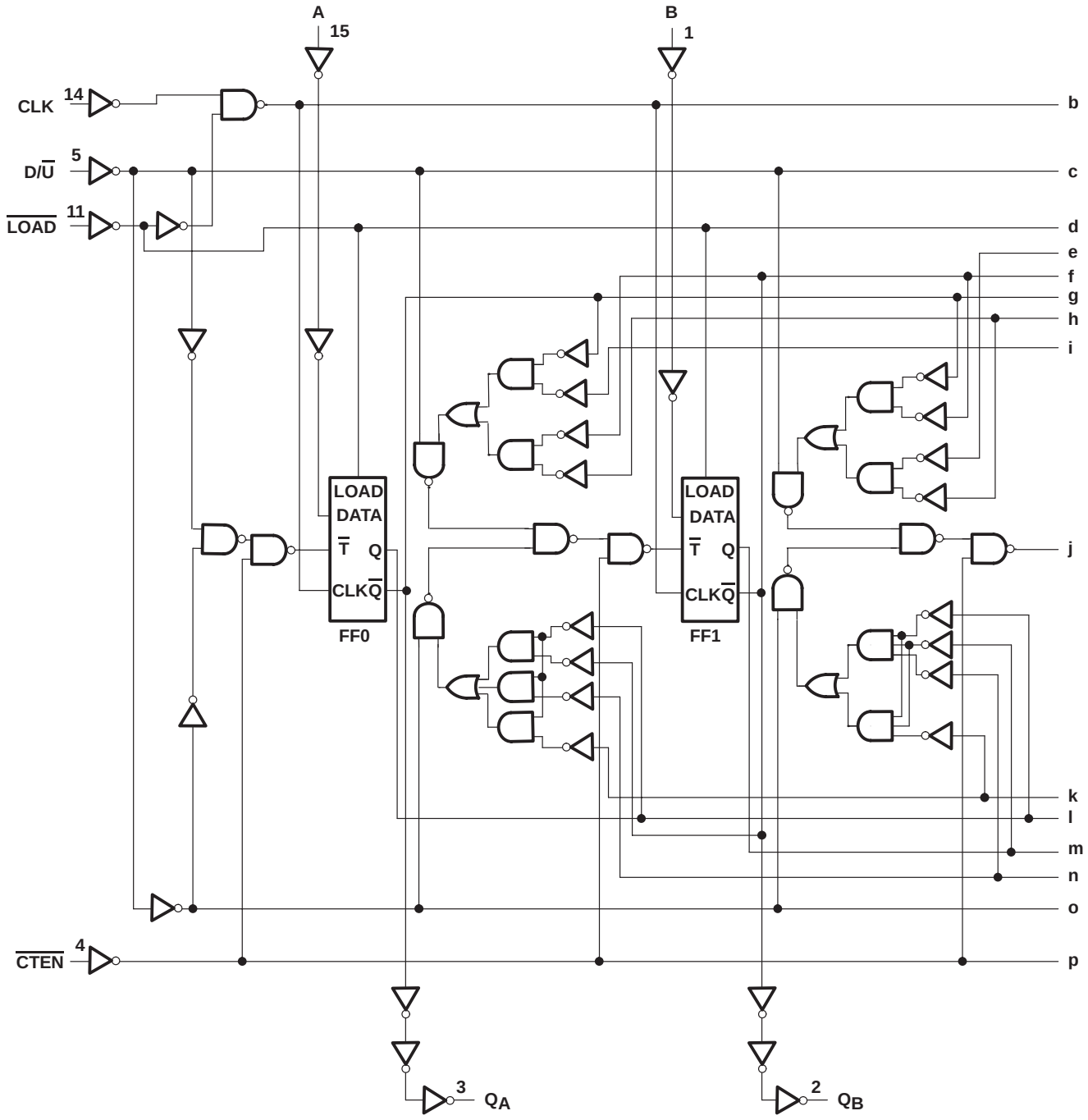
If a decade counter is preset to an illegal state or assumes an illegal state when power is applied, it returns to the normal sequence in one or two counts, as shown in the state diagrams (see Figure 3).

FUNCTION TABLE

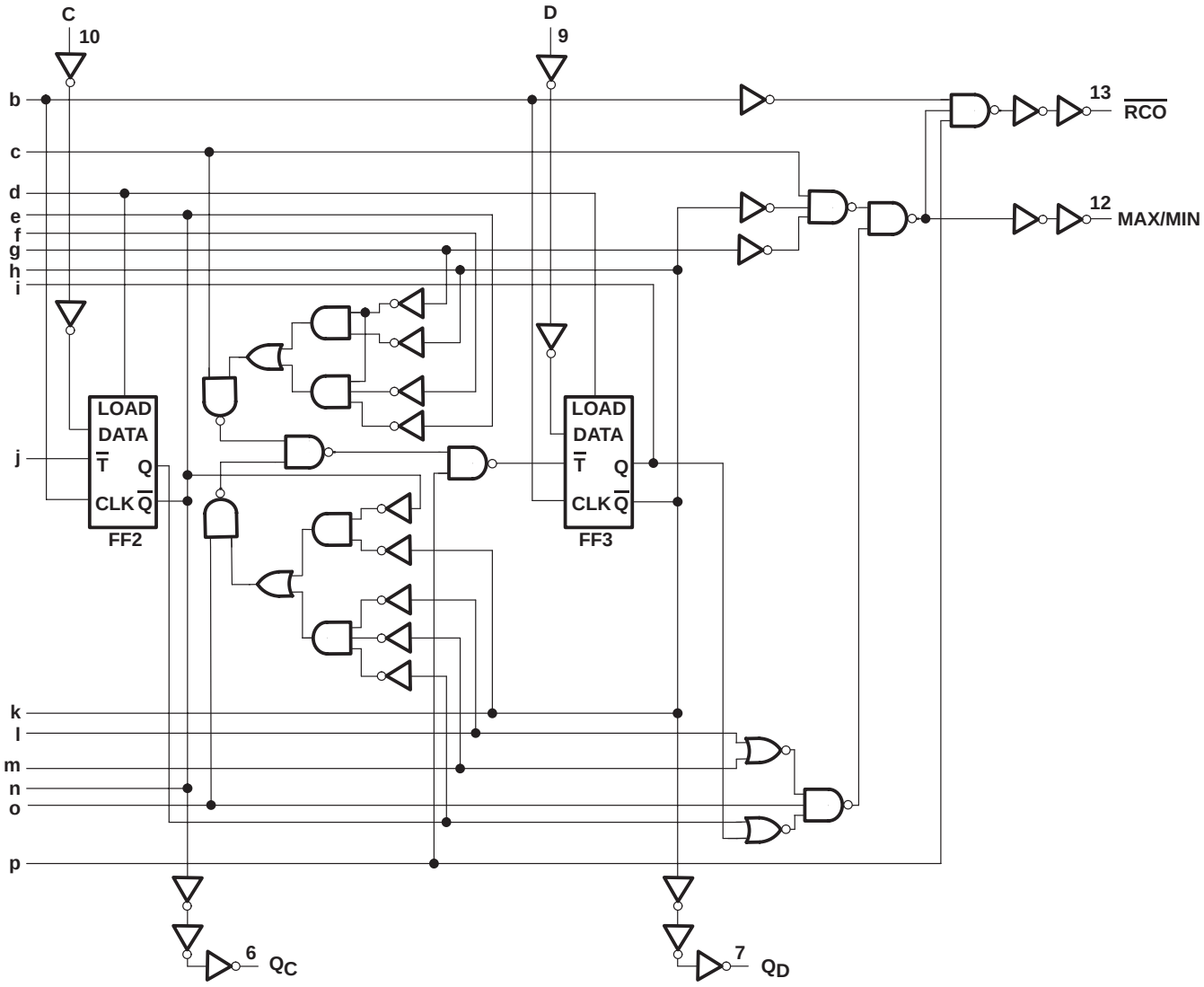
INPUTS				FUNCTION
$\overline{LOAD}$	$\overline{CTEN}$	D/$\overline{U}$	CLK	
H	L	L	⌐	Count up
H	L	H	⌐	Count down
L	X	X	X	Asynchronous preset
H	H	X	X	No change

D/$\overline{U}$ or $\overline{CTEN}$ should be changed only when clock is high.
X = Don't care
⌐ Low-to-high clock transition

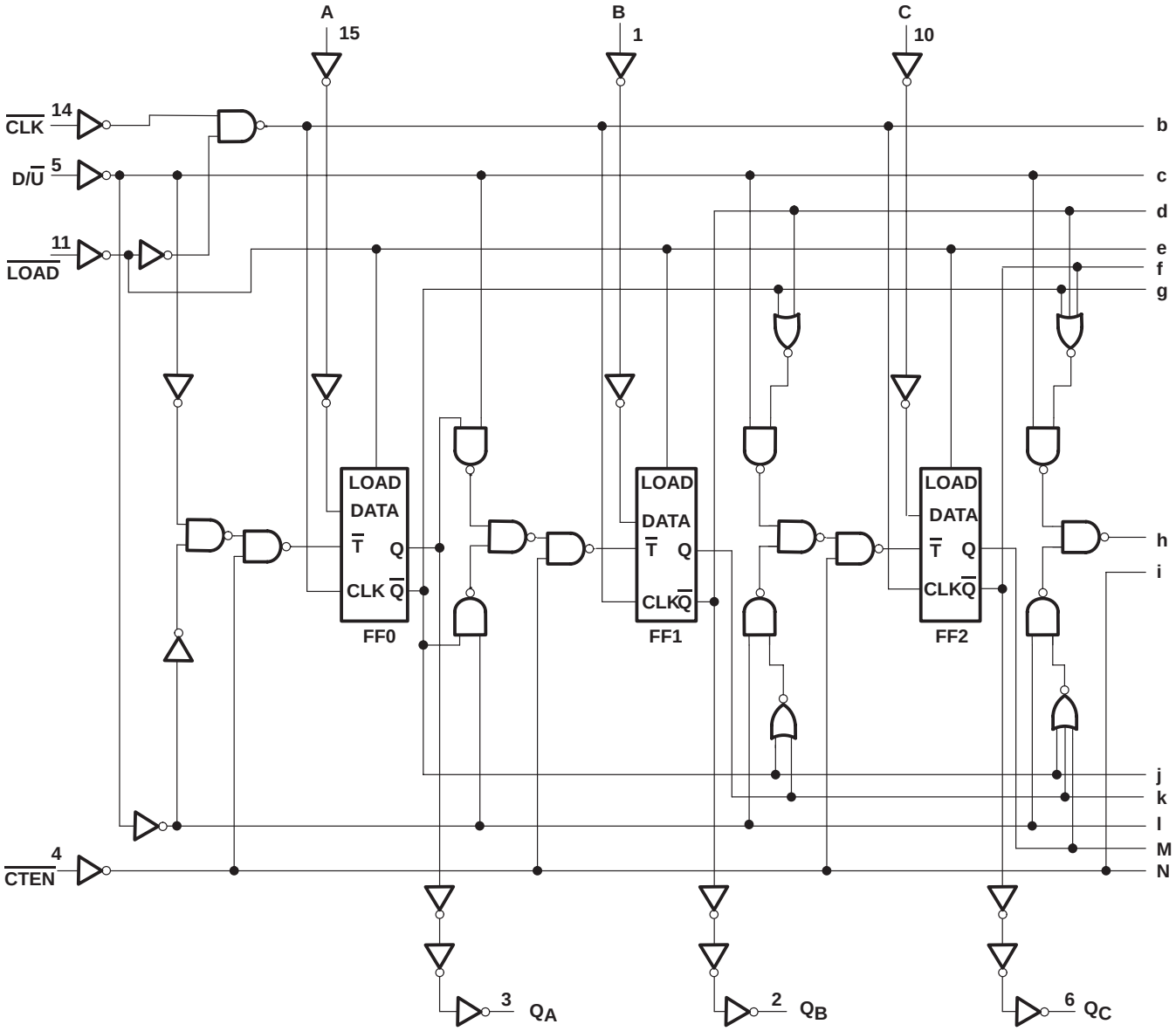
'HC190 logic diagram



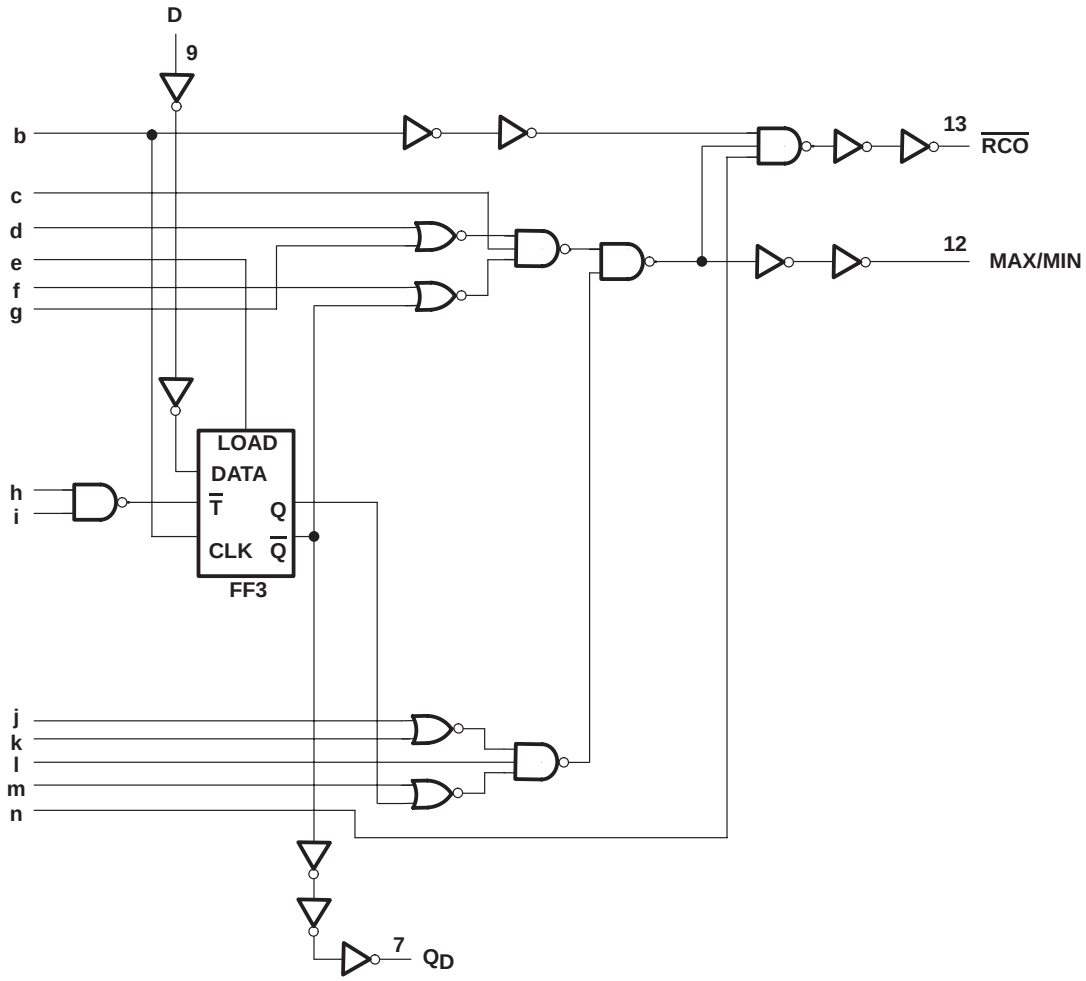
'HC190 logic diagram (continued)



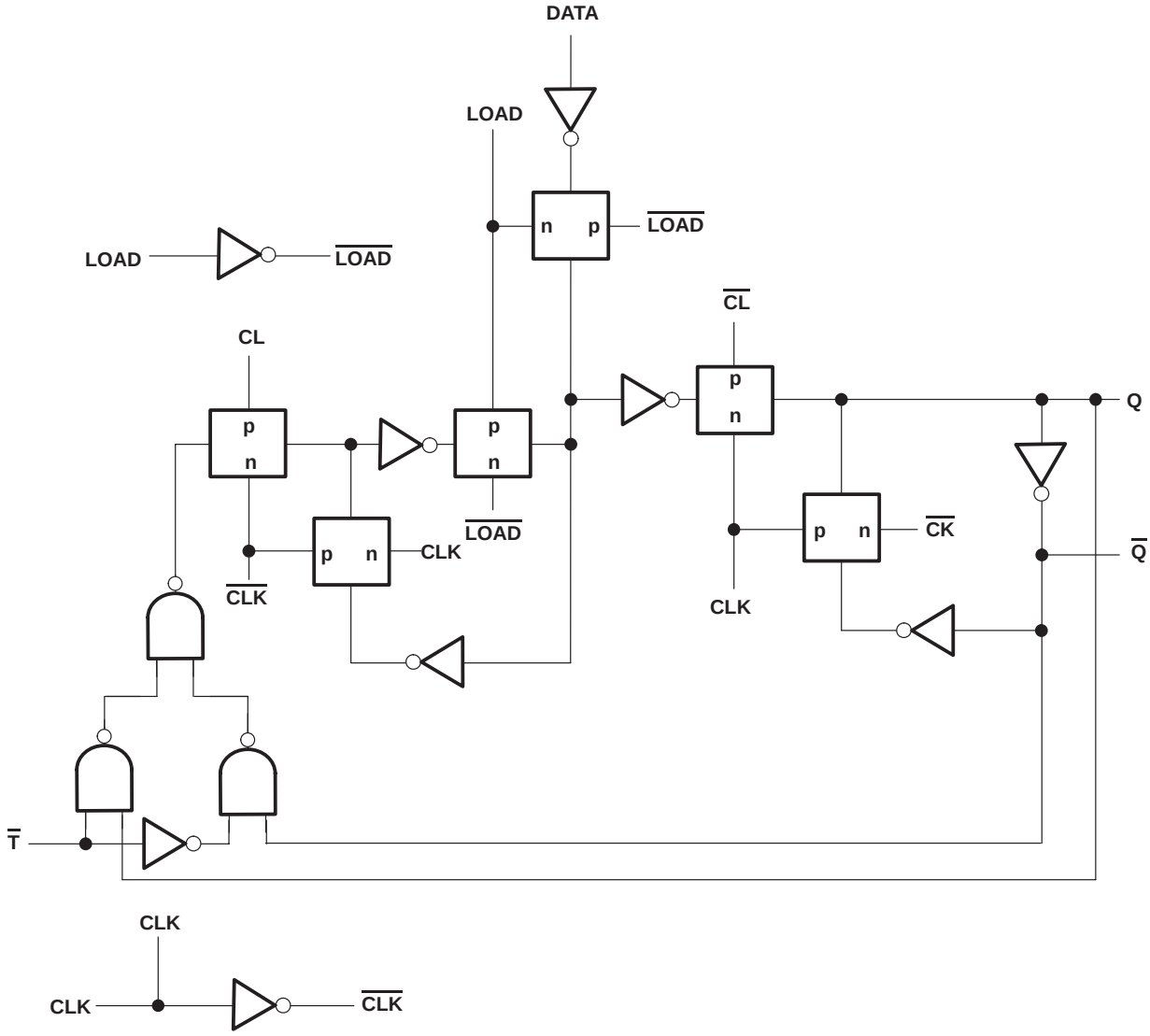
'HC191, 'HCT191 logic diagram



'HC191, 'HCT191 logic diagram (continued)



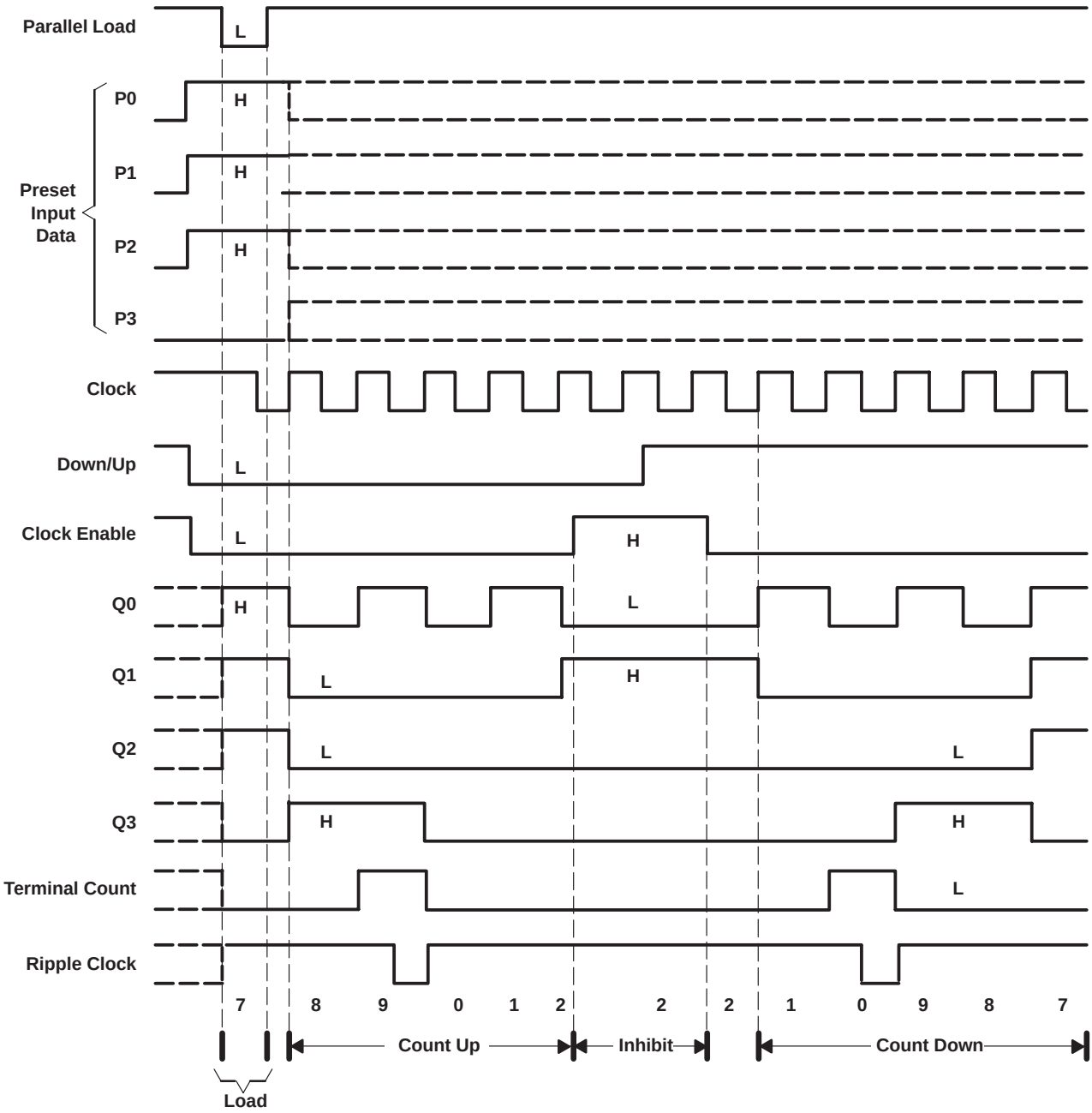
'HC190 and 'HC191/HCT191 flip-flop



typical load, count, and inhibit sequence for ’HC190

The following sequence is illustrated below:

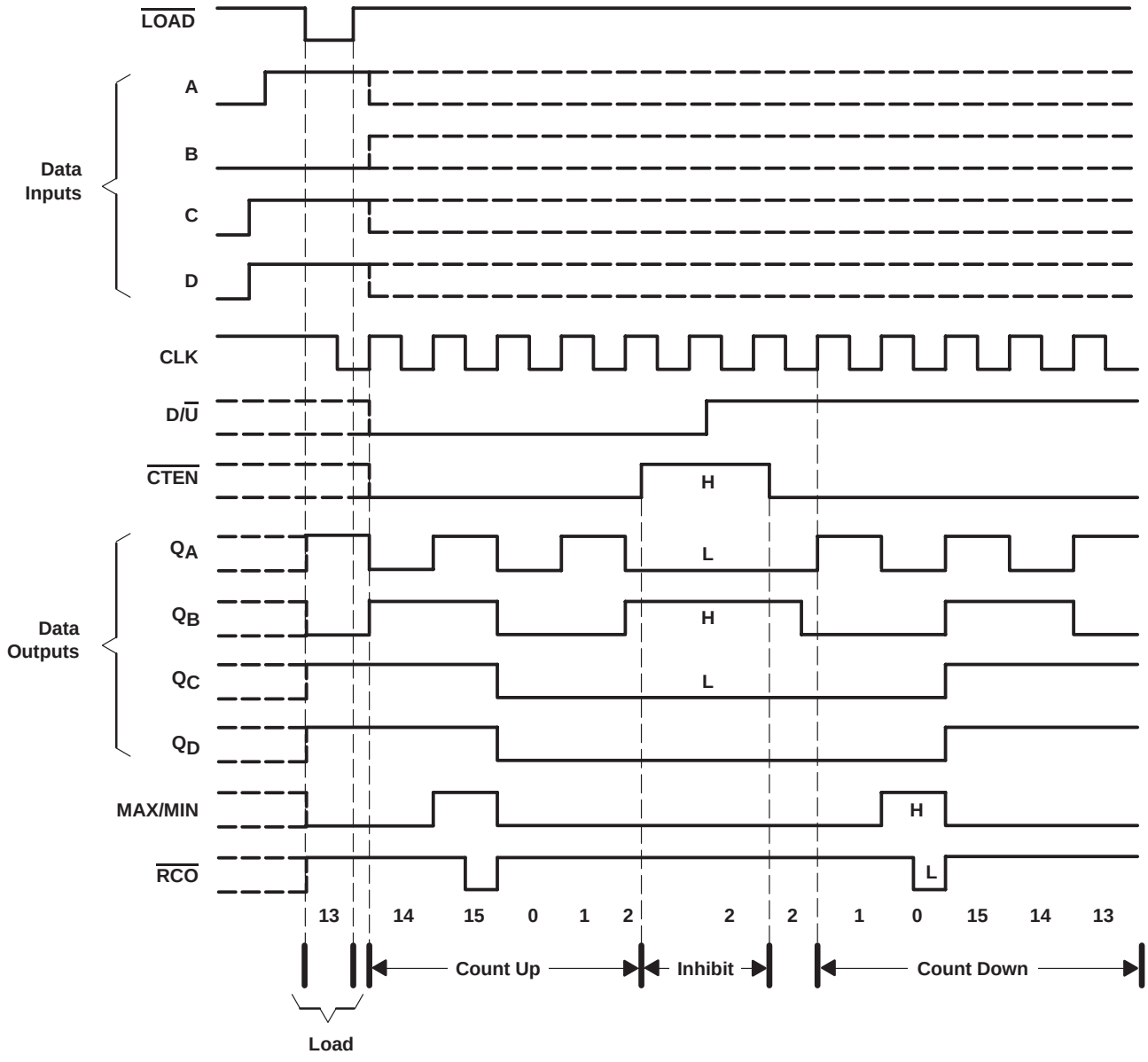
1. Load (preset) to BCD 7
2. Count up to 8, 9 (maximum), 0, 1, and 2
3. Inhibit
4. Count down to 1, 0 (minimum), 9, 8, and 7



typical load, count, and inhibit sequence for ’HC191 and ’HCT191

The following sequence is illustrated below:

1. Load (preset) to binary 13
2. Count up to 14, 15 (maximum), 0, 1, and 2
3. Inhibit
4. Count down to 1, 0 (minimum), 15, 14, and 13



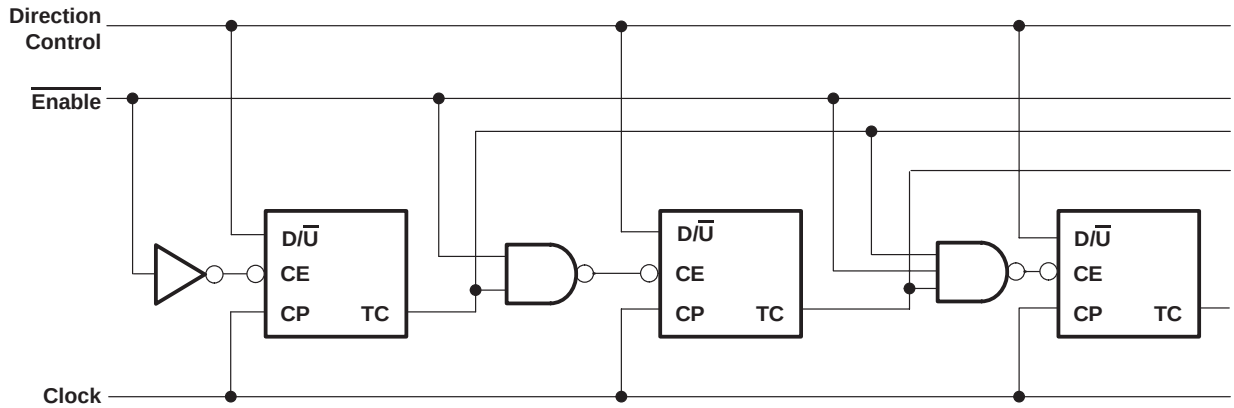


Figure 1. 'HC190 Synchronous n-Stage Counter With Parallel Gated Terminal Count

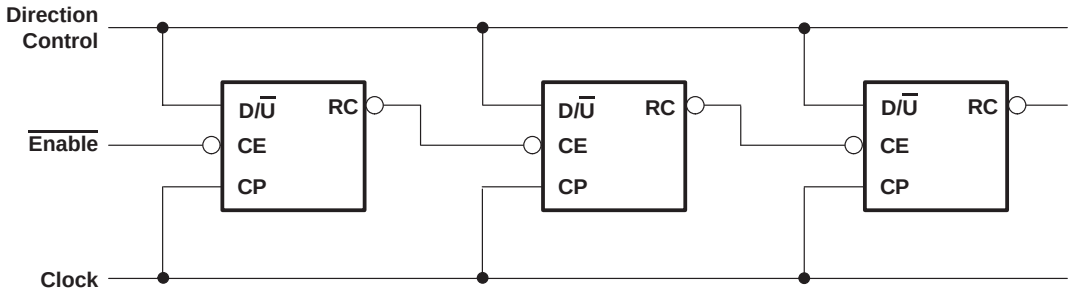
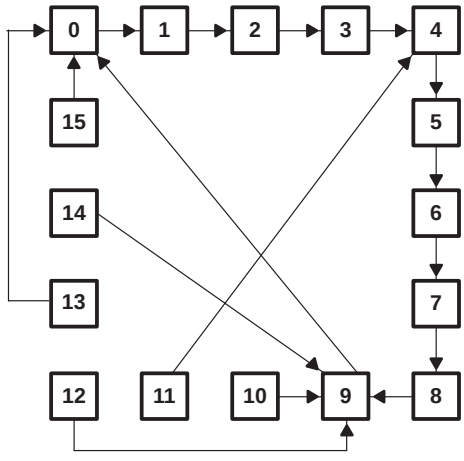
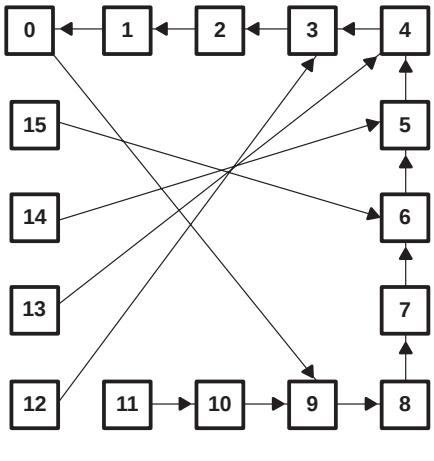


Figure 2. 'HC191, 'HCT191 Synchronous n-Stage Counter With Parallel Gated Terminal Count



Count Up

NOTE: Illegal states in BCD counters corrected in one count



Count Down

NOTE: Illegal states in BCD counters corrected in one or two counts

Figure 3. 'HC190 State Diagram

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1) . . . . . ±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1) . . . . . ±20 mA
Continuous output drain current per output, I_O ($V_O = 0$ to V_{CC}) . . . . . ±35 mA
Continuous output source or sink current per output, I_O ($V_O = 0$ to V_{CC}) . . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): E package . . . . . 67°C/W
M package . . . . . 73°C/W
NS package . . . . . 64°C/W
PW package . . . . . 108°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions for ’HC190 and ’HC191 (see Note 3)

			T_A = 25°C		T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	6	2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		1.5		V
		V_{CC} = 4.5 V	3.15		3.15		3.15		
		V_{CC} = 6 V	4.2		4.2		4.2		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5		0.5	V
		V_{CC} = 4.5 V		1.35		1.35		1.35	
		V_{CC} = 6 V		1.8		1.8		1.8	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	0	V_{CC}	V
t_t	Input transition (rise and fall) time	V_{CC} = 2 V		1000		1000		1000	ns
		V_{CC} = 4.5 V		500		500		500	
		V_{CC} = 6 V		400		400		400	

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

recommended operating conditions for ’HCT191 (see Note 4)

		T_A = 25°C		T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage	2		2		2		V
V_{IL}	Low-level input voltage		0.8		0.8		0.8	V
V_I	Input voltage		V_{CC}		V_{CC}		V_{CC}	V
V_O	Output voltage		V_{CC}		V_{CC}		V_{CC}	V
t_t	Input transition (rise and fall) time		500		500		500	ns

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

’HC190, ’HC191

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C		T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
V_{OH}	V_I = V_{IH} or V_{IL}	I_{OH} = −20 μA	2 V	1.9		1.9		1.9		V
			4.5 V	4.4		4.4		4.4		
			6 V	5.9		5.9		5.9		
		I_{OH} = −4 mA	4.5 V	3.98		3.7		3.84		
		I_{OH} = −5.2 mA	6 V	5.48		5.2		5.34		
V_{OL}	V_I = V_{IH} or V_{IL}	I_{OL} = 20 μA	2 V		0.1		0.1		0.1	V
			4.5 V		0.1		0.1		0.1	
			6 V		0.1		0.1		0.1	
		I_{OL} = 4 mA	4.5 V		0.26		0.4		0.33	
		I_{OL} = 5.2 mA	6 V		0.26		0.4		0.33	
I_I	V_I = V_{CC} or 0		6 V		±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or 0, I_O = 0		6 V		8		160		80	μA
C_i					10		10		10	pF

’HCT191

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	V_I = V_{IH} or V_{IL}	I_{OH} = −20 μA	4.5 V	4.4			4.4		4.4		V
		I_{OH} = −4 mA		3.98			3.7		3.84		
V_{OL}	V_I = V_{IH} or V_{IL}	I_{OL} = 20 μA	4.5 V			0.1		0.1		0.1	V
		I_{OL} = 4 mA				0.26		0.4		0.33	
I_I	V_I = V_{CC} to GND		5.5 V			±0.1		±1		±1	μA
I_{CC}	V_I = V_{CC} or 0, I_O = 0		5.5 V			8		160		80	μA
ΔI_{CC}†	One input at V_{CC} − 2.1 V, Other inputs at 0 or V_{CC}		4.5 V to 5.5 V		100	360		490		450	μA
C_i						10		10		10	pF

† Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

HCT INPUT LOADING TABLE

INPUTS	UNIT LOADS
A-D	0.4
CLK	1.5
$\overline{\text{LOAD}}$	1.5
D/$\overline{\text{U}}$	1.2
$\overline{\text{CTEN}}$	1.5

Unit load is ΔI_{CC} limit specified in electrical characteristics table, (e.g., 360 μA max at 25°C).

'HC190, 'HC191 timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

			V_{CC}	T_A = 25°C		T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency†		2 V		6		4		5	MHz
			4.5 V		30		20		25	
			6 V		35		23		29	
t_w	Pulse duration	$\overline{LOAD}$ low	2 V	80		120		100		ns
			4.5 V	16		24		20		
			6 V	14		20		17		
		CLK high or low	2 V	100		150		125		
			4.5 V	20		30		25		
			6 V	17		26		21		
t_{su}	Setup time	Data before $\overline{LOAD}$↑	2 V	60		90		75		ns
			4.5 V	12		18		15		
			6 V	10		15		13		
		$\overline{CTEN}$ before CLK↑	2 V	60		90		75		
			4.5 V	12		18		15		
			6 V	10		15		13		
		D/$\overline{U}$ before CLK↑	2 V	90		135		115		
			4.5 V	18		27		23		
			6 V	15		23		20		
t_h	Hold time	Data before $\overline{LOAD}$↑	2 V	2		2		2		ns
			4.5 V	2		2		2		
			6 V	2		2		2		
		$\overline{CTEN}$ before CLK↑	2 V	2		2		2		
			4.5 V	2		2		2		
			6 V	2		2		2		
		D/$\overline{U}$ before CLK↑	2 V	0		0		0		
			4.5 V	0		0		0		
			6 V	0		0		0		
t_{rec}	Recovery time	$\overline{LOAD}$ inactive before CLK↑	2 V	60		90		75		ns
			4.5 V	12		18		15		
			6 V	10		15		13		

† Applies to noncascaded operation only. With cascaded counters, clock-to-terminal count propagation delays, $\overline{CTEN}$-to-clock setup times, and $\overline{CTEN}$-to-clock hold times determine maximum clock frequency. For example, with these HC devices:

$$f_{max}(CLK) = \frac{1}{\text{CLK-to-MAX/MIN propagation delay} + \overline{CTEN}\text{-to-CLK setup time} + \overline{CTEN}\text{-to-CLK hold time}} = \frac{1}{42 + 12 + 2} \approx 18 \text{ MHz}$$

’HC190, ’HC191

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V_{CC}	T_A = 25°C			T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
					MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}				2 V	6			4		5		MHz
				4.5 V	30			20		25		
				6 V	35			23		29		
t_{pd}	$\overline{LOAD}$	Q	C_L = 50 pF	2 V			195		295		245	ns
				4.5 V			39		59		49	
				6 V			33		50		42	
			C_L = 15 pF	5 V		16						
	A, B, C, or D	Q	C_L = 50 pF	2 V			175		265		220	
				4.5 V			35		53		44	
				6 V			30		45		37	
			C_L = 15 pF	5 V		14						
	CLK	Q	C_L = 50 pF	2 V			170		255		215	
				4.5 V			34		51		43	
				6 V			29		43		37	
			C_L = 15 pF	5 V		14						
	CLK	$\overline{RCO}$	C_L = 50 pF	2 V			125		190		155	
				4.5 V			25		38		31	
				6 V			21		32		26	
			C_L = 15 pF	5 V		10						
	CLK	MAX/MIN	C_L = 50 pF	2 V			210		315		265	
				4.5 V			42		63		53	
				6 V			36		54		45	
			C_L = 15 pF	5 V		18						
	D/$\overline{U}$	$\overline{RCO}$	C_L = 50 pF	2 V			150		225		190	
				4.5 V			30		45		38	
				6 V			26		38		33	
			C_L = 15 pF	5 V		12						
	D/$\overline{U}$	MAX/MIN	C_L = 50 pF	2 V			165		250		205	
				4.5 V			33		50		41	
				6 V			28		43		35	
			C_L = 15 pF	5 V		13						
	$\overline{CTEN}$	$\overline{RCO}$	C_L = 50 pF	2 V			125		190		155	
				4.5 V			25		38		31	
				6 V			21		32		26	
			C_L = 15 pF	5 V		10						
t_t		Any	C_L = 50 pF	2 V			75		110		95	ns
				4.5 V			15		22		19	
				6 V			13		19		16	

'HCT191

timing requirements over recommended operating free-air temperature range V_{CC} = 4.5 V (unless otherwise noted) (see Figure 5)

			T_A = 25°C		T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			30		20		25	MHz
t_w	Pulse duration	$\overline{LOAD}$ low	16		24		20		ns
		CLK high or low	20		30		25		
t_{su}	Setup time	Data before $\overline{LOAD}\uparrow$	12		18		15		ns
		$\overline{CTEN}$ before CLK$\uparrow$	12		18		15		
		D/$\overline{U}$ before CLK$\uparrow$	18		27		23		
t_h	Hold time	Data before $\overline{LOAD}\uparrow$	2		2		2		ns
		$\overline{CTEN}$ before CLK$\uparrow$	2		2		2		
		D/$\overline{U}$ before CLK$\uparrow$	0		0		0		
t_{rec}	Recovery time	$\overline{LOAD}$ inactive before CLK$\uparrow$	12		18		15		ns

'HCT191

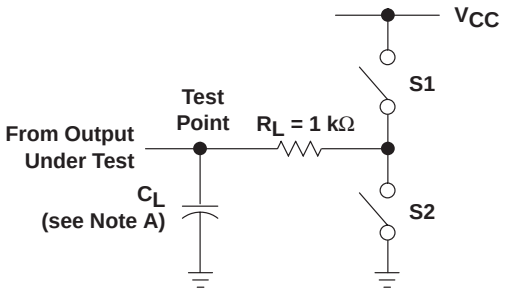
switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V_{CC}	T_A = 25°C			T_A = −55°C TO 125°C		T_A = −40°C TO 85°C		UNIT
					MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}				4.5 V	30			20		25		MHz
t_{pd}	$\overline{LOAD}$	Q	C_L = 50 pF	4.5 V			40		60		50	ns
			C_L = 15 pF	5 V		17						
	A, B, C, or D	Q	C_L = 50 pF	4.5 V			38		57		48	
			C_L = 15 pF	5 V		16						
	CLK	$\overline{RCO}$	C_L = 50 pF	4.5 V			35		53		44	
			C_L = 15 pF	5 V		14						
	CLK	Q	C_L = 50 pF	4.5 V			27		41		34	
			C_L = 15 pF	5 V		11						
	CLK	MAX/MIN	C_L = 50 pF	4.5 V			42		63		53	
			C_L = 15 pF	5 V		18						
	D/$\overline{U}$	$\overline{RCO}$	C_L = 50 pF	4.5 V			30		45		38	
			C_L = 15 pF	5 V		12						
	D/$\overline{U}$	MAX/MIN	C_L = 50 pF	4.5 V			38		57		48	
			C_L = 15 pF	5 V		16						
	$\overline{CTEN}$	$\overline{RCO}$	C_L = 50 pF	4.5 V			27		41		34	
			C_L = 15 pF	5 V		11						
t_t		Any	C_L = 50 pF	4.5 V			15		22		19	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

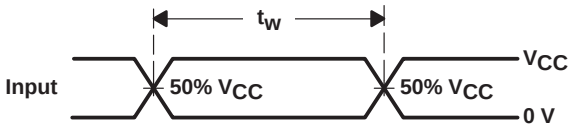
PARAMETER			TYP	UNIT
C_{pd}	Power dissipation capacitance	'HC190	59	pF
		'HC191	55	
		'HCT191	68	

PARAMETER MEASUREMENT INFORMATION − ’HC190, ’HC191

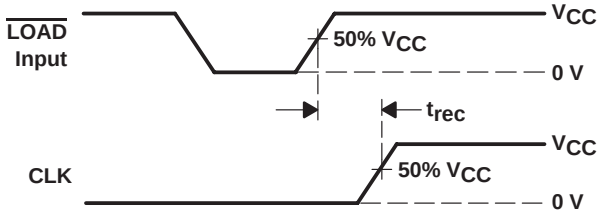


LOAD CIRCUIT

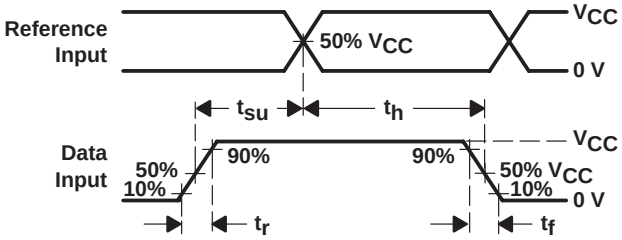
PARAMETER		S1	S2
t_{en}	t_{PZH}	Open	Closed
	t_{PZL}	Closed	Open
t_{dis}	t_{PHZ}	Open	Closed
	t_{PLZ}	Closed	Open
t_{pd} or t_t		Open	Open



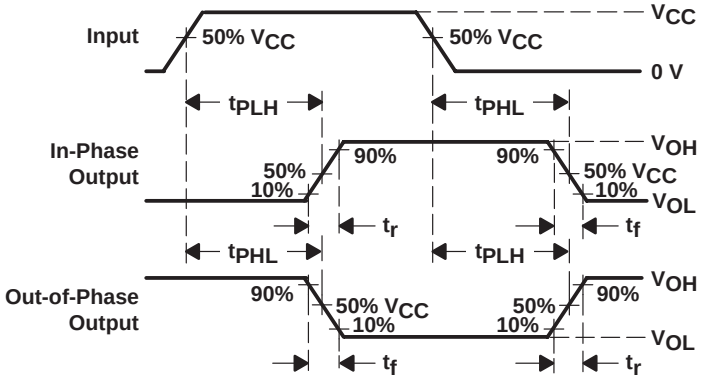
VOLTAGE WAVEFORMS
PULSE DURATION



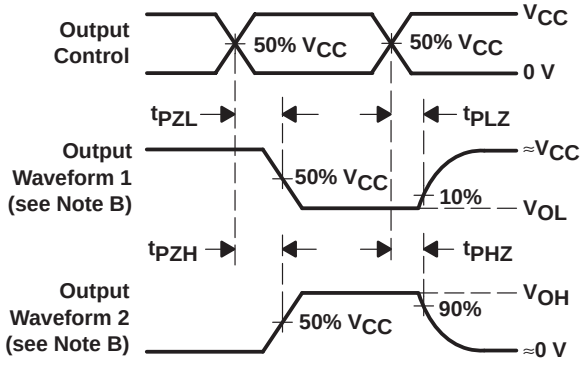
VOLTAGE WAVEFORMS
RECOVERY TIME



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

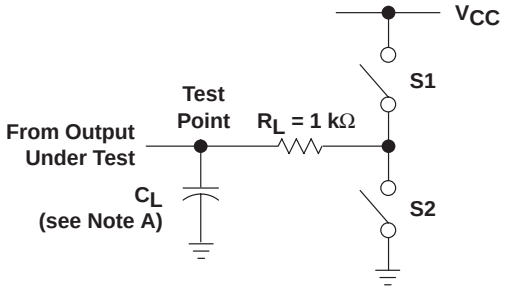


VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
E. The outputs are measured one at a time with one input transition per measurement.
F. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
G. t_{PZL} and t_{PZH} are the same as t_{en}.
H. t_{PLH} and t_{PHL} are the same as t_{pd}.

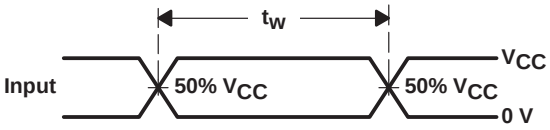
Figure 4. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION − ’HCT191

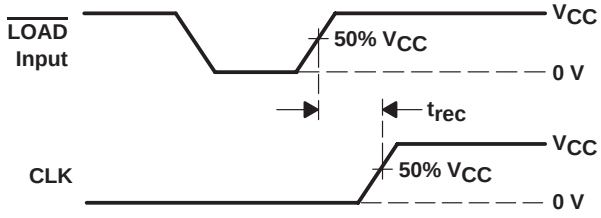


LOAD CIRCUIT

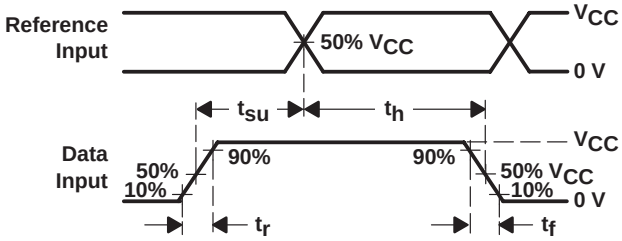
PARAMETER		S1	S2
t_{en}	t_{PZH}	Open	Closed
	t_{PZL}	Closed	Open
t_{dis}	t_{PHZ}	Open	Closed
	t_{PLZ}	Closed	Open
t_{pd} or t_t		Open	Open



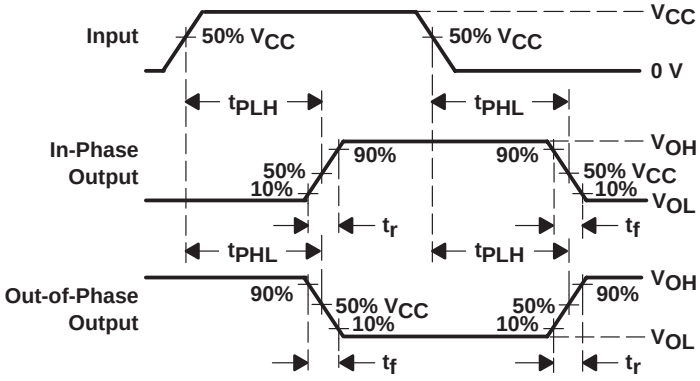
VOLTAGE WAVEFORMS
PULSE DURATION



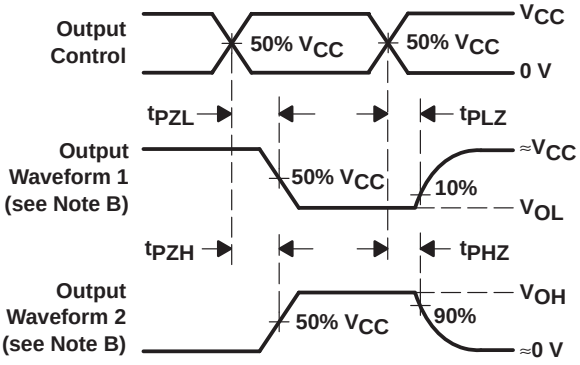
VOLTAGE WAVEFORMS
RECOVERY TIME



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS
OUTPUT ENABLE AND DISABLE TIMES

NOTES: A. C_L includes probe and test-fixture capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r = 6 ns, t_f = 6 ns.
D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
E. The outputs are measured one at a time with one input transition per measurement.
F. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
G. t_{PZL} and t_{PZH} are the same as t_{en}.
H. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 5. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
5962-8867101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
5962-8994601EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Call TI	
CD54HC190F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD54HC191F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD54HCT191F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	
CD74HC190E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC190EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC190NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC190PWTG4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HC191EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
CD74HC191M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HC191MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT191E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT191EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
CD74HCT191M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT191ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
CD74HCT191MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

OTHER QUALIFIED VERSIONS OF CD54HC190, CD54HC191, CD54HCT191, CD74HC190, CD74HC191, CD74HCT191 :

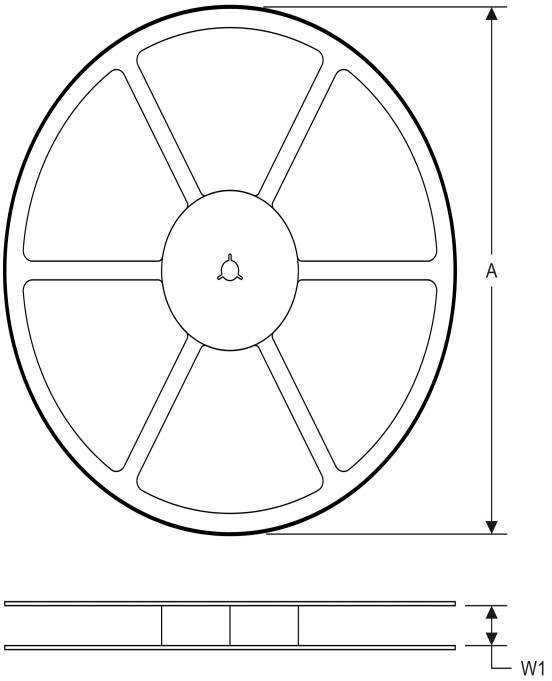
- Catalog: CD74HC190, CD74HC191, CD74HCT191
- Military: CD54HC190, CD54HC191, CD54HCT191

NOTE: Qualified Version Definitions:

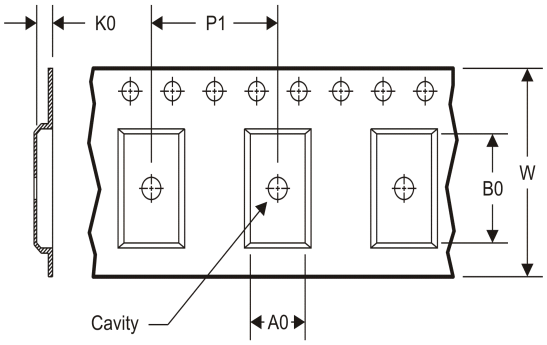
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



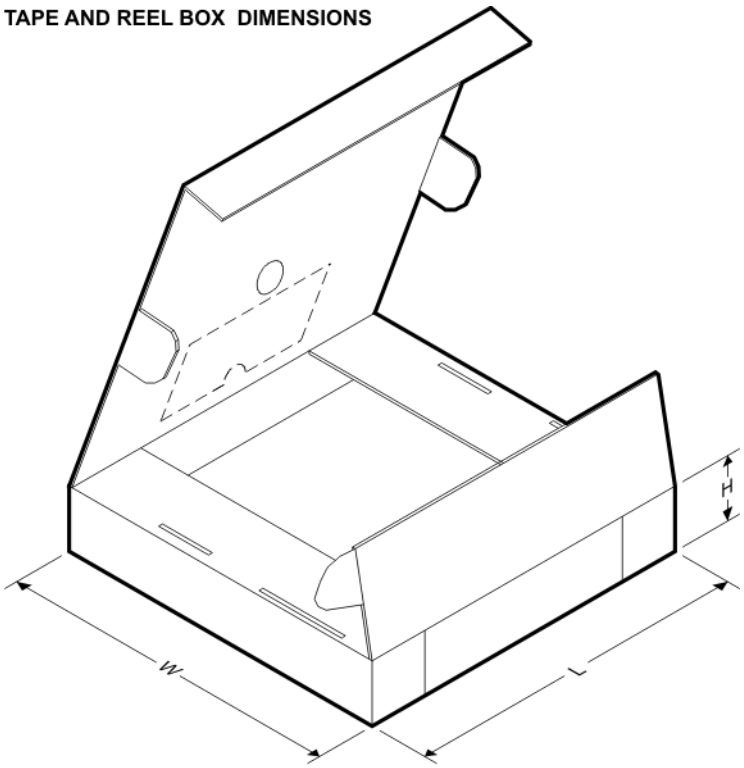
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC190NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC190PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC190PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC191M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



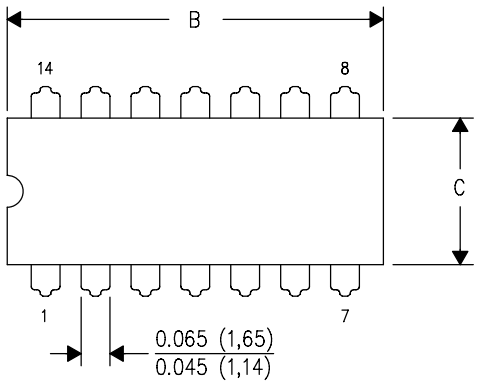
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC190NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC190PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
CD74HC190PWT	TSSOP	PW	16	250	367.0	367.0	35.0
CD74HC191M96	SOIC	D	16	2500	333.2	345.9	28.6

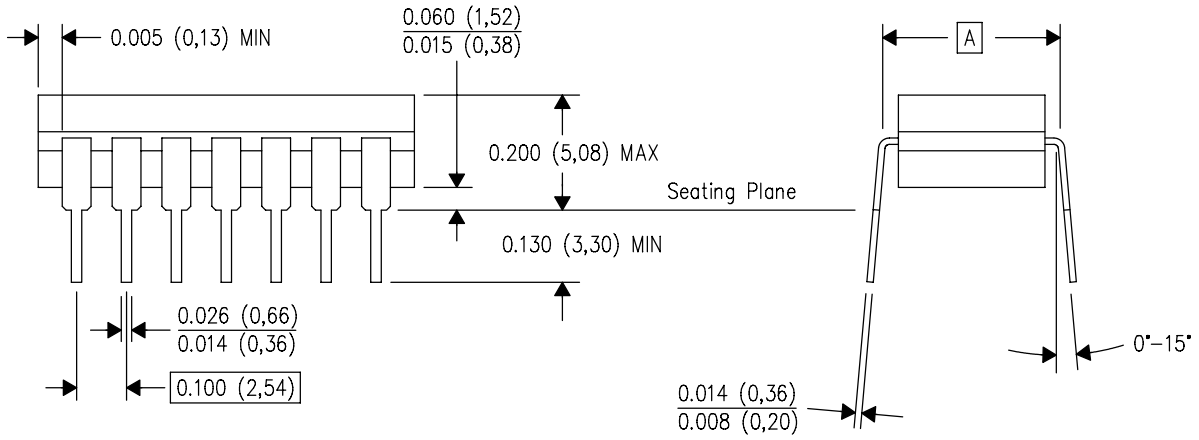
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



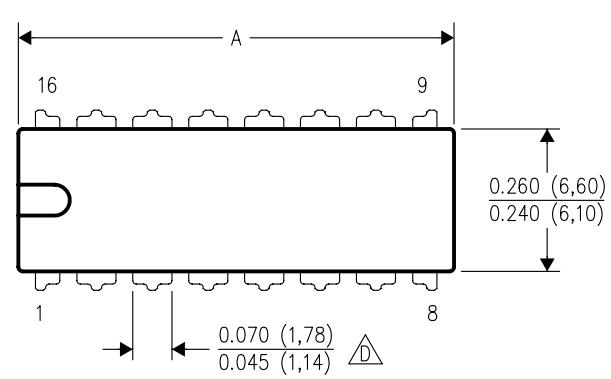
4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

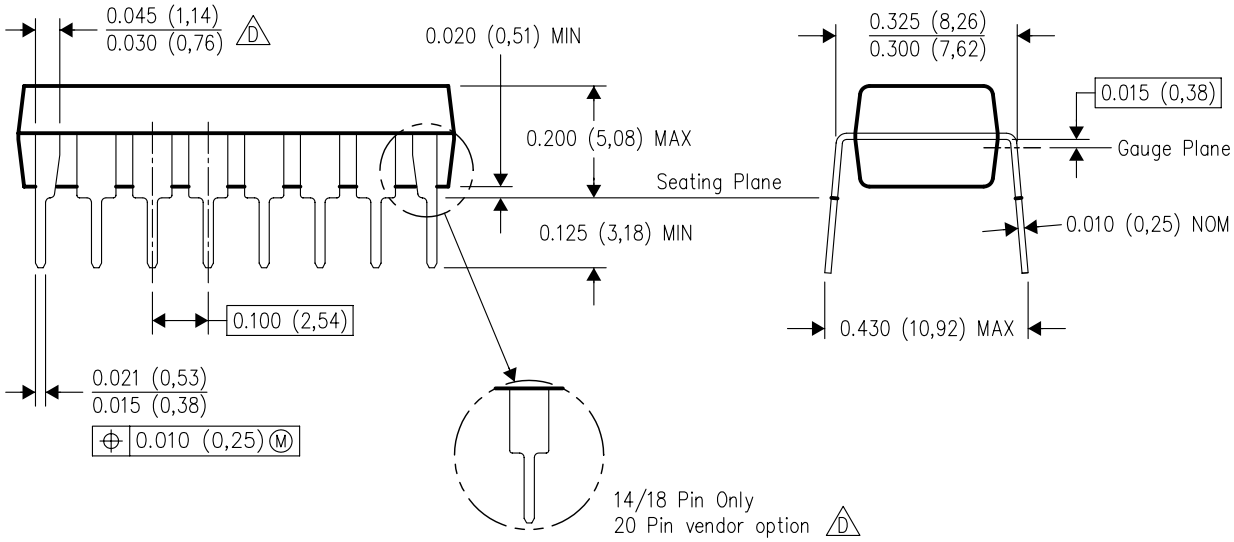
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



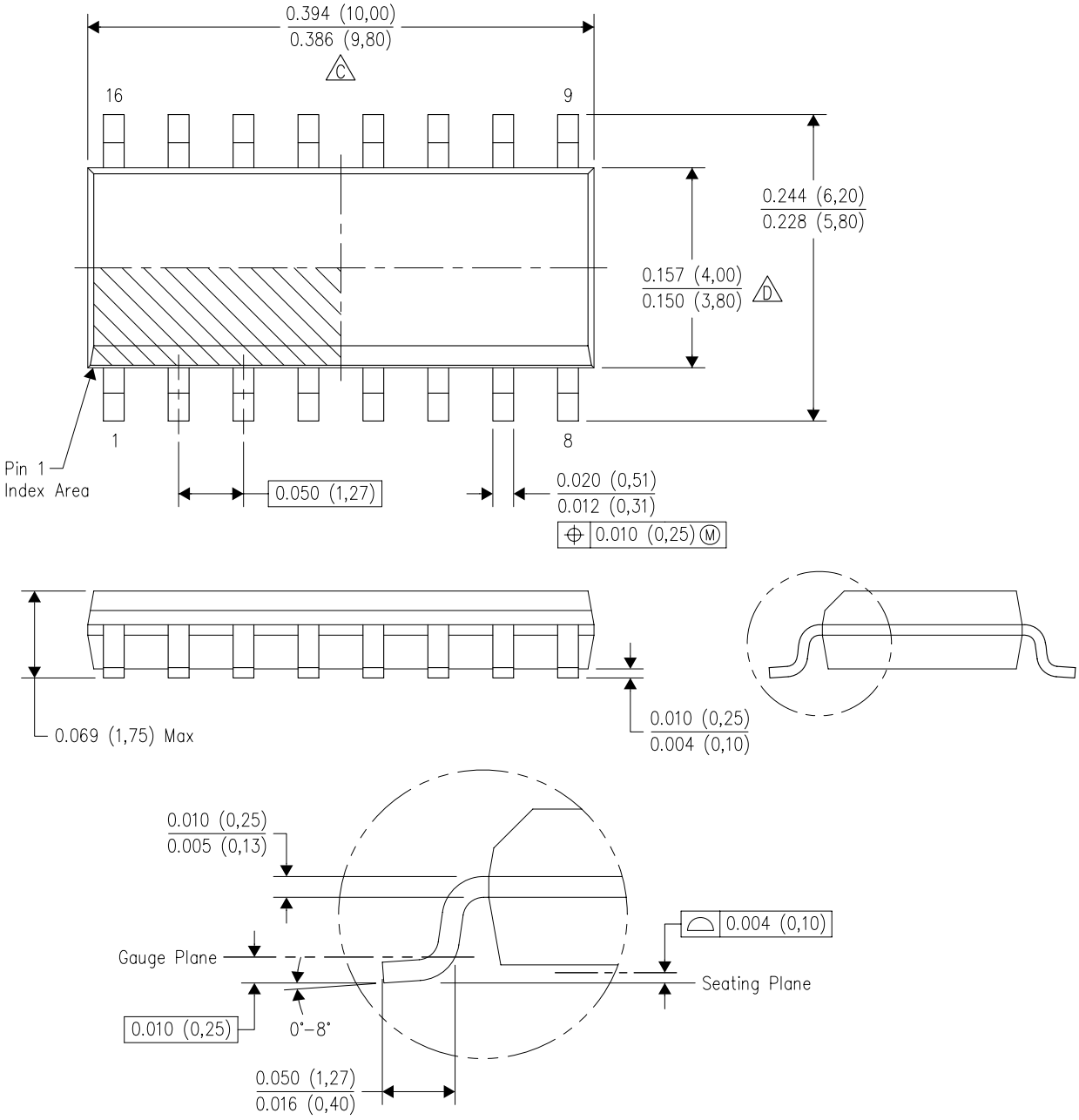
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

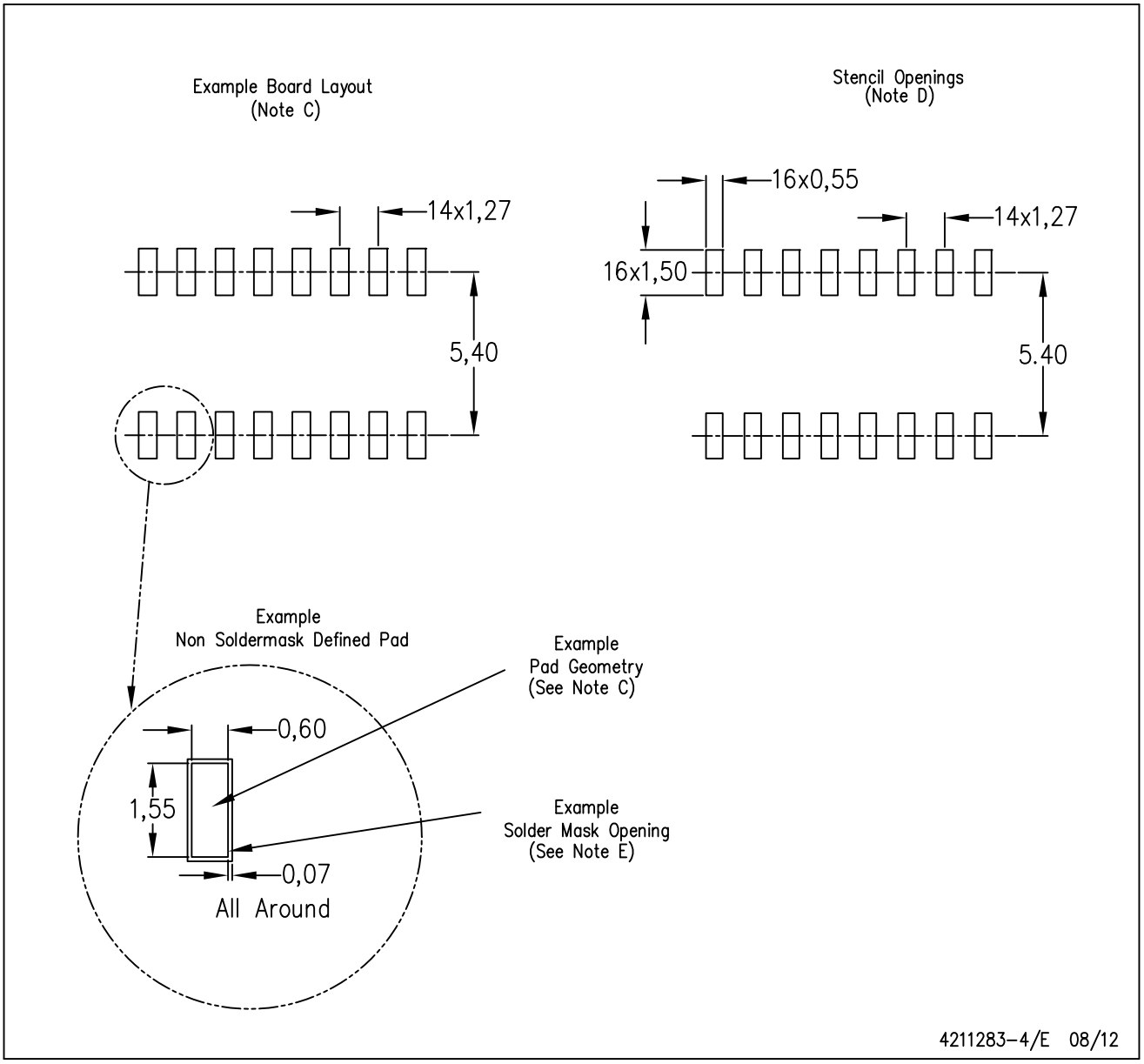
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



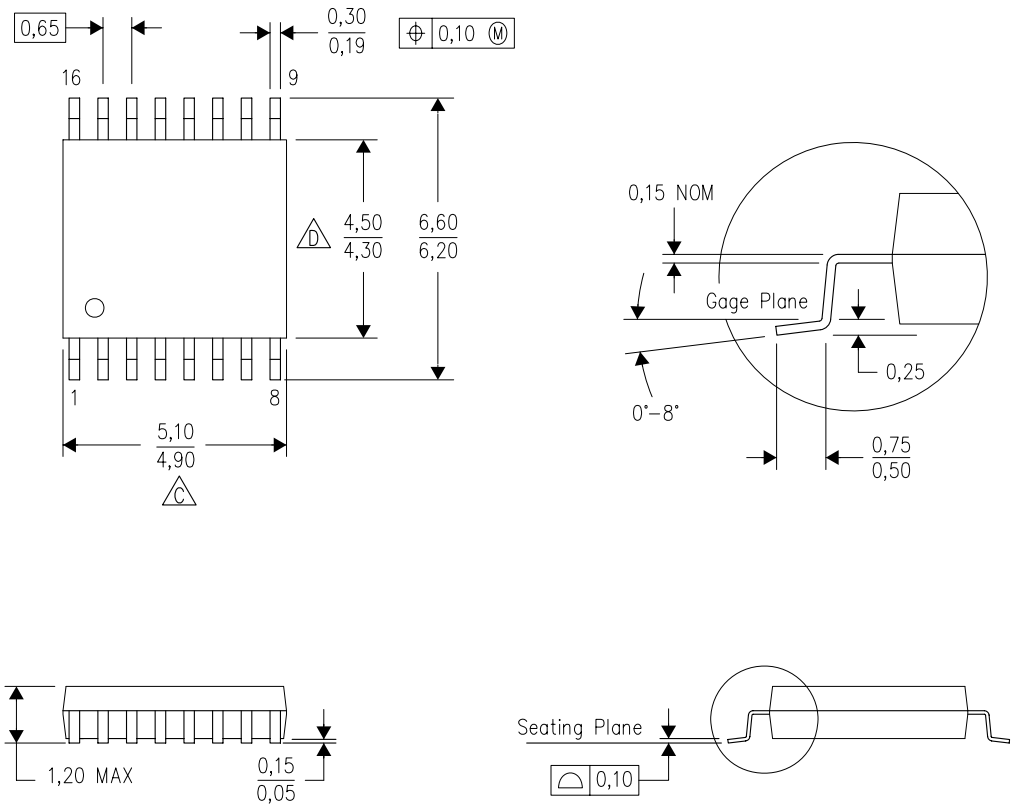
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

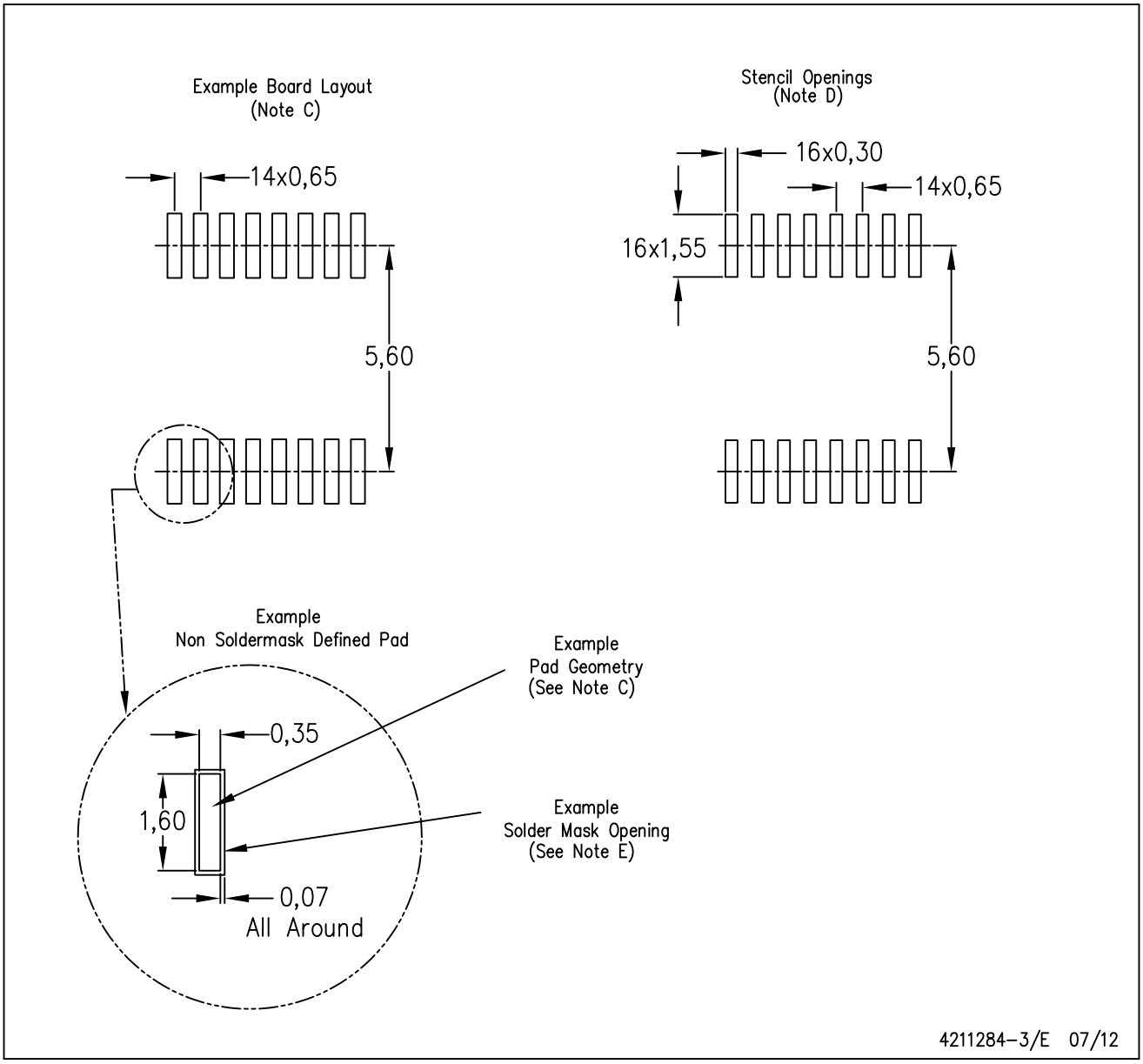
PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



4040064–4/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G16) PLASTIC SMALL OUTLINE

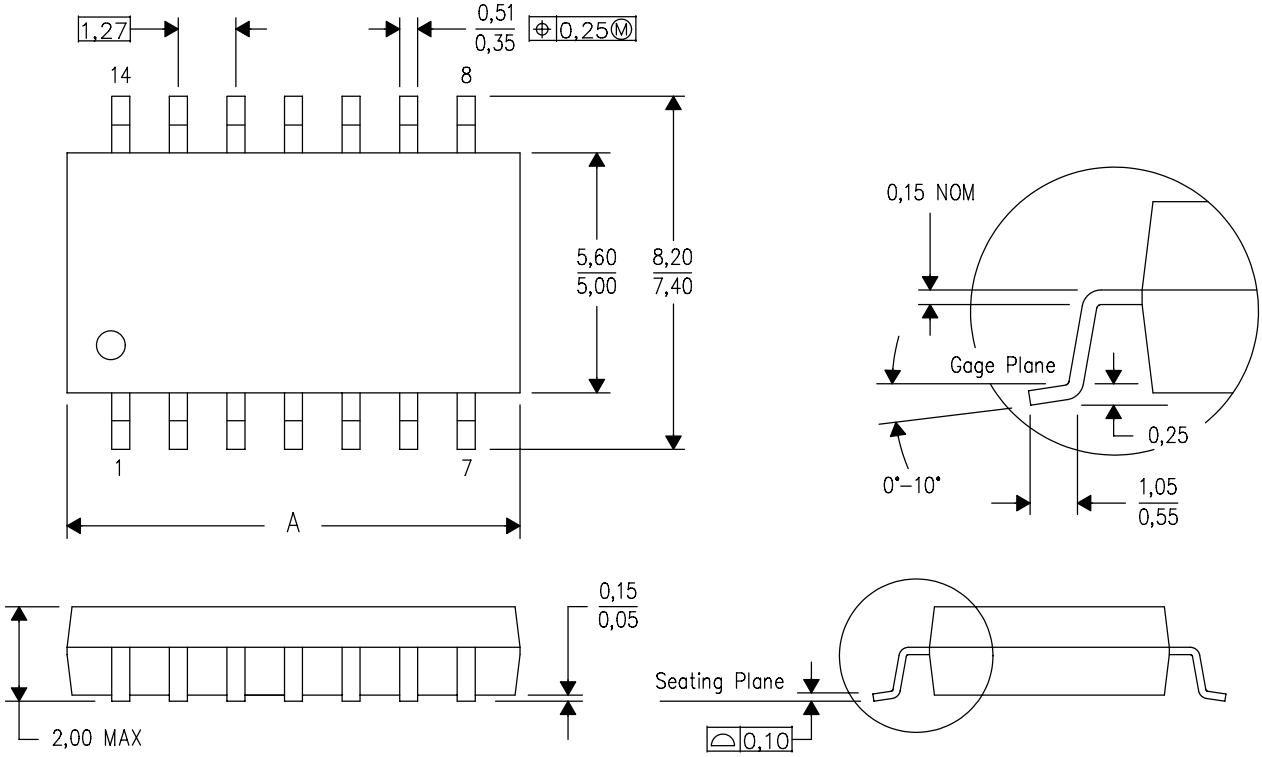


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Стандарт Электрон Связь

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,
Промышленная ул, дом № 19, литера Н,
помещение 100-Н Офис 331